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DS75361 Dual TTL-to-MOS Driver

General Description

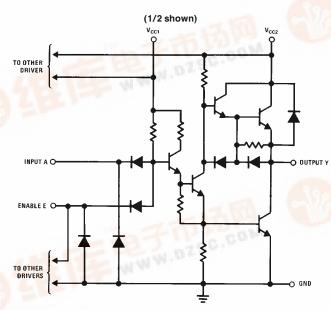
The DS75361 is a monolithic integrated dual TTL-to-MOS driver interface circuit. The device accepts standard TTL input signals and provides high-current and high-voltage output levels for driving MOS circuits. It is used to drive address, control, and timing inputs for several types of MOS RAMs including the 1103 and MM5270 and MM5280.

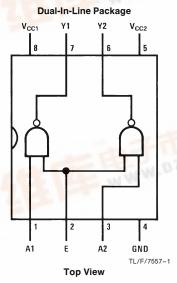
The DS75361 operates from standard TTL 5V supplies and the MOS V_{SS} supply in many applications. The device has been optimized for operation with V_{CC2} supply voltage from 16V to 20V; however, it is designed for use over a much wider range of V_{CC2} .

Features

- Capable of driving high-capacitance loads
- Compatible with many popular MOS RAMs
- V_{CC2} supply voltage variable over wide range to 24V
- Diode-clamped inputs
- TTL compatible
- Operates from standard bipolar and MOS supplies
- High-speed switching
- Transient overdrive minimizes power dissipation
- Low standby power dissipation

Schematic and Connection Diagrams





Order Number DS75361N See NS Package Number N08E

TL/F/7557-3

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TL/F/7557

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Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Maximum Power Dissipation* at 25°C

Molded Package 1022 mW

Lead Temperature 1/16 inch from Case for 10 Seconds: N or P Package

*Derate molded package 8.2 mW/° above about 25°C.

Operating Conditions

 Min
 Max
 Units

 Supply Voltage (V_{CC1})
 4.75
 5.25
 V

 Supply Voltage (V_{CC2})
 4.75
 24
 V

 Operating Temperature (T_A)
 0
 +70
 °C

200°C

Electrical Characteristics (Notes 2 and 3)

Symbol	Parameter	Conditions		Min	Тур	Max	Units
V _{IH}	High-Level Input Voltage			2			V
V _{IL}	Low-Level Input Voltage					0.8	V
VI	Input Clamp Voltage	$I_{I} = -12 \text{mA}$				-1.5	V
V _{OH}	High-Level Output Voltage	$V_{IL} = 0.8V, I_{OH} = -50 \mu A$		V _{CC2} - 1	V _{CC2} - 0.7		٧
		$V_{IL} = 0.8V, I_{OH} = -10 \text{ mA}$		V _{CC2} - 2.3	V _{CC2} - 1.8		V
V _{OL}	Low-Level Output Voltage	$V_{IH} = 2V$, $I_{OL} = 10 \text{ mA}$			0.15	0.3	V
		$V_{CC2} =$ 15V to 24V, $V_{IH} =$ 2V, $I_{OL} =$ 40 mA			0.25	0.5	٧
Vo	Output Clamp Voltage	$V_I = 0V$, $I_{OH} = 20 \text{ mA}$				V _{CC2} + 1.5	٧
II	Input Current at Maximum Input Voltage	V _I = 5.5V				1	mA
liH	High-Level Input Current	V _I = 2.4V	A Inputs			40	μΑ
			E Input			80	μΑ
I _{IL}	Low-Level Input Current	V _I = 0.4V	A Inputs		-1	-1.6	mA
			E Input		-2	-3.2	mA
I _{CC1(H)}	Supply Current from V _{CC1} , Both Outputs High	V _{CC1} = 5.25V,	Vaa- = 24V		2	4	mA
I _{CC2(H)}	Supply Current from V _{CC2} , Both Outputs High	All Inputs at 0V,				0.5	mA
I _{CC1(L)}	Supply Current from V _{CC1} , Both Outputs Low	V 5 25V	V _{CC2} = 24V, No Load		16	24	mA
I _{CC2(L)}	Supply Current from V _{CC2} , Both Outputs Low	All Inputs at 5V,			7	11	mA
I _{CC2(S)}	Supply Current from V _{CC2} , Stand-by Condition	$V_{CC1} = 0V$, All Inputs at 5V,				0.5	mA

Note 1: "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. Except for "Operating Temperature Range" they are not meant to imply that the devices should be operated at these limits. The table of "Electrical Characteristics" provides conditions for actual device operation.

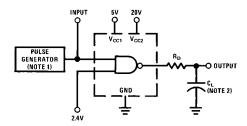
Note 2: Unless otherwise specified min/max limits apply across the 0°C to +70°C range for the DS75361. All typical values are for $T_A = 25$ °C and $V_{CC1} = 5V$ and $V_{CC2} = 20V$.

Note 3: All currents into device pins shown as positive, out of device pins as negative, all voltages referenced to ground unless otherwise noted. All values shown as max or min on absolute value basis.

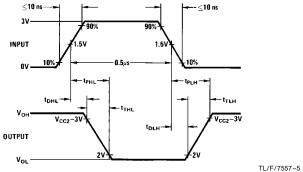
Note 4: This rating applies between the A input of either driver and the common E input.

Switching Characteristics V _{CC1} = 5V, V _{CC2} = 20V, T _A = 25°C										
Symbol	Parameter	Conditions	Min	Тур	Max	Units				
t _{DLH}	Delay Time, Low-to-High Level Output			11	20	ns				
t _{DHL}	Delay Time, High-to-Low Level Output	$C_{L} = 390 pF,$		10	18	ns				
t _{TLH}	Transition Time, Low-to-High Level Output	$R_D = 10\Omega$		25	40	ns				
t _{THL}	Transition Time, High-to-Low Level Output	(Figure 1)		21	35	ns				
tPLH	Propagation Delay Time, Low-to-High Level Output		10	36	55	ns				
t _{PHL}	Propagation Delay Time, High-to-Low Level Output		10	31	47	ns				

AC Test Circuit and Switching Time Waveforms

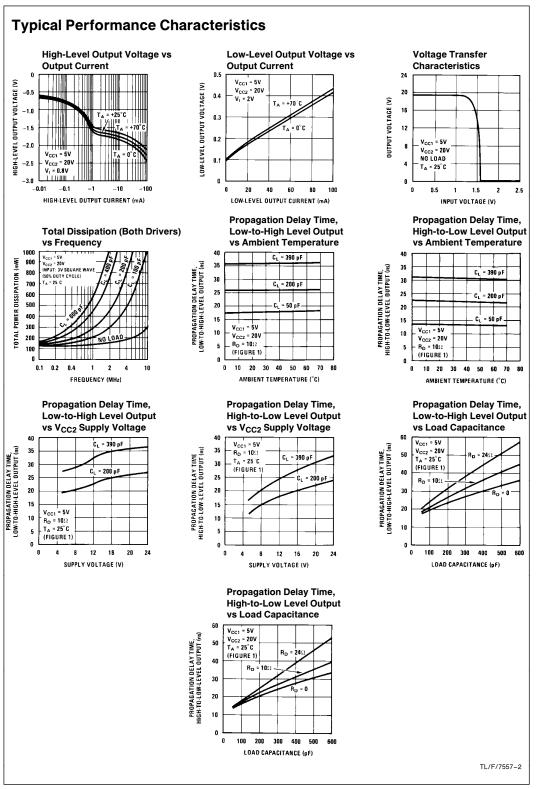


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Note 1: The pulse generator has the following characteristics: PRR = 1 MHz, $Z_{OUT}=50\Omega$. Note 2: C_L includes probe and jig capacitance.

FIGURE 1. Switching Times, Each Driver



Typical Applications

The fast switching speeds of this device may produce undesirable output transient overshoot because of load or wiring inductance. A small series damping resistor may be used to reduce or eliminate this output transient overshoot. The

optimum value of the damping resistor to use depends on the specific load characteristics and switching speed. A typical value would be between 10Ω and 30Ω (Figure 3).

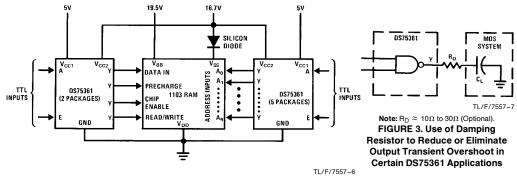


FIGURE 2. Interconnection of DS75361 Devices with 1103 RAM

Thermal Information

POWER DISSIPATION PRECAUTIONS

Significant power may be dissipated in the DS75361 driver when charging and discharging high-capacitance loads over a wide voltage range at high frequencies. The total dissipation curve shows the power dissipated in a typical DS75361 as a function of load capacitance and frequency. Average power dissipated by this driver can be broken into three components:

$$P_{T(AV)} = P_{DC(AV)} + P_{C(AV)} + P_{S(AV)}$$

where $P_{DC(AV)}$ is the steady-state power dissipation with the output high or low, $P_{C(AV)}$ is the power level during charging or discharging of the load capacitance, and $P_{S(AV)}$ is the power dissipation during switching between the low and high levels. None of these include energy transferred to the load and all are averaged over a full cycle.

The power components per driver channel are:

$$\begin{split} P_{DC(AV)} &= \frac{P_L t_L + P_H t_H}{T} \\ P_{C(AV)} &\approx C \, V_C{}^2 \, f \\ P_{S(AV)} &= \frac{P_L H t_L H + P_{HL} t_{HL}}{T} \end{split}$$

where the times are defined in Figure 4.

 P_L , P_H , P_{LH} , and P_{HL} are the respective instantaneous levels of power dissipation and C is load capacitance.

The DS75361 is so designed that P_S is a negligible portion of P_T in most applications. Except at very high frequencies, $t_L + t_H \gg t_{LH} + t_{HL}$ so that P_S can be neglected. The total dissipation curve for no load demonstrates this point. The power dissipation contributions from both channels are then added together to obtain total device power.

The following example illustrates this power calculation technique. Assume both channels are operating identically with C = 200 pF, f = 2 MHz, $V_{\rm CC1}=5V,\,V_{\rm CC2}=20V,$ and duty cycle = 60% outputs high (t_H/T = 0.6). Also, assume $V_{\rm OH}=19.3V,\,V_{\rm OL}=0.1V,\,P_{\rm S}$ is negligible, and that the current from $V_{\rm CC2}$ is negligible when the output is high.

On a per-channel basis using data sheet values:

$$\begin{split} P_{DC(AV)} &= \left[\ (5V) \left(\frac{2 \text{ mA}}{2} \right) + (20V) \left(\frac{0 \text{ mA}}{2} \right) \ \right] (0.6) \ + \\ &\left[(5V) \left(\frac{16 \text{ mA}}{2} \right) + (20V) \left(\frac{7 \text{ mA}}{2} \right) \ \right] (0.4) \end{split}$$

 $P_{DC(AV)} = 47 \text{ mW per channel}$

 $P_{C(AV)} \approx$ (200 pF) (19.2V)² (2 MHz)

 $P_{C(AV)} \approx$ 148 mW per channel.

For the total device dissipation of the two channels:

 $P_{T(AV)} \approx 2 (47 + 148)$

 $P_{T(AV)} \approx 390$ mW typical for total package.

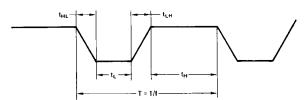
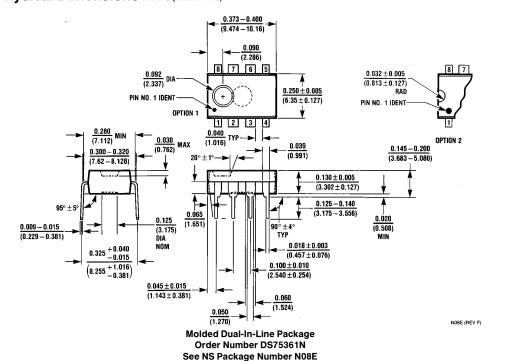


FIGURE 4. Output Voltage Waveform

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Physical Dimensions inches (millimeters)



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